

# **SPECIFICATION**

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SPEC. NO.: PS-52001-XXXXXX-XXX REVISION: D

PRODUCT NAME: 1.0mm PITCH BTB SMT S/T D/R CONNECTOR

PRODUCT NO: 52001 series; 52002 series; 52005 series; EB00A

series; EB00B series

PREPARED: CHECKED: APPROVED:

TSO I CHIAO Chen, Chun Yuan Huang Kuo Hua

DATE: DATE:

2022/03/31 2022/03/31 2022/03/31



EB00A series; EB00B series

TITLE: 1.0 MM PITCH BTB SMT S/T D/R CONNECTOR

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EB00A series; EB00B series

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# 1 Revision History

Rev.	ECN#	Revision Description	Prepared	Date
Α	ECN-005826	NEW SPEC	Leishanjun	2020/05/23
В	ECN-005928	ADD EB00B series	Leishanjun	2021/10/28
С	ECN-007033	ADD EB00A series	TSO I CHIAO	2022/02/16
D	ECN-012237	產品使用溫度提高至 105℃	TSO I CHIAO	2023/03/31



EB00A series; EB00B series

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#### 2 SCOPE

This specification covers performance, tests and quality requirements for 1.0mm pitch BTB connector.

#### 3 APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

#### 4 REQUIREMENTS

- 4.1 Design and Construction
  - 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
  - 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.
- 4.2 Materials and Finish
  - 4.2.1 Plug Terminal: High performance copper alloy (Phosphor Bronze)
    Receptacle Terminal: High performance copper alloy (Beryllium copper)
    Fitting Nail: High performance copper alloy (Brass)
  - 4.2.2
- Finish: (a) Contact Area: Refer to the drawing.
  - (b) Under plate: Refer to the drawing.
  - (c) Solder area: Refer to the drawing.
- 4.2.3 Housing: Thermoplastic High Temp., UL94V-0
- 4.3 Ratings
  - 4.3.1 Working Voltage Less than 36 Volts AC (per pin)
  - 4.3.2 Voltage: 50 Volts AC (per pin)
  - 4.3.3 Current: 1Amperes (per pin)
  - 4.3.4 Operating Temperature : -40°C to +105°C



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## 5 Performance

## 5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard								
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.								
ELECTRICAL										
Item	Requirement	Standard								
Low Level Contact Resistance	25 m Ω Max.(initial)per contact ΔR 10 m Ω Max.	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)								
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)								
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)								
Temperature Rise	30°C Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70,METHOD1,CONDITION1)								
	MECHANICAL									
Item	Requirement	Standard								
Durability	200 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)								



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		11.76	17								
		Unit:		,							
			ting	Unm	!						
	Pins		(Max)								
			Final								
	11		1.38								
	21	2.63	2.63	0.95	Operation Speed:						
					25.4 ± 3 mm/						
Mating / Unmating Force	s					Measure the force required to					
						mate/Unmate	e connector.				
						(EIA-364-13)					
		<u> </u>									
						Operation Sp	eed:				
Contact	0.12kgf	MIN				25.4 ± 3 mm/	25.4 ± 3 mm/minute.				
Retention Force	0.12Kgl	VIIIV.				Measure the	contact retention				
						force with Tensile strength tester.					
							Operation Speed :				
Fitting Nail /Housing	0 2kaf M	0.2kgf MIN.					$25.4 \pm 3$ mm/minute.				
Retention Force	U.ZKYI IV						Measure the contact retention				
							force with tester.				
						l load condition					
						shall be 100 mA maximum for					
						all contacts. Subject to a simple					
						harmonic mo					
							0.76mm (1.52mm				
							al excursion) in				
						tween the limits of					
Vibration	1 µs Ma	x.				10 and 55 Hz. The entire frequency range, from 10 to 55					
					Hz and return to 10 Hz, shall be traversed in approximately 1						
							minute. This motion shall be				
				applied for 2 hours in each of							
							three mutually perpendicular				
						directions.	<b>7</b> 1				
						(EIA-364-28 (	Condition I)				
							d connectors to				
		50 G's (peak value) half-sine									
		1 μs Max.					shock pulses of 11 millisecond				
							duration. Three shocks in ea				
							I be applied along				
Shock (Mechanical)	1 µs Ma						ually perpendicular				
,						axes of the test specimen (18					
							shocks). The electrical load				
							condition shall be 100mA				
							maximum for all contacts.				
							(EIA-364-27, test condition A)				



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ENVIRONMENTAL								
Item	Requirement	Standard						
Resistance to <b>Reflow</b> Soldering Heat	See Product Qualification and Test Sequence Group 9 (Lead Free)	Pre Heat: 150°C~180°C, 60~120sec. Heat: 230°C Min., 40sec Min. Peak Temp.: 260°CMax, 10sec Max.						
Thermal Shock	See Product Qualification and Test Sequence Group 4	-40 +0/-3 °C, 30 minutes +105 +3/-0 °C, 30 minutes (EIA-364-32, test condition I)						
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector						
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to						
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution						
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)						

Note. Flowing Mixed Gas shell be conduct by customer request.



EB00A series; EB00B series

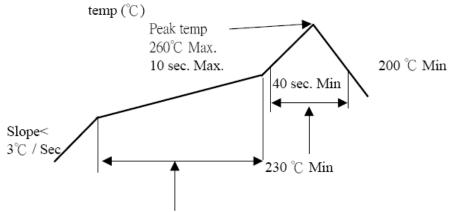
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## **6 INFRARED REFLOW CONDITION**

#### 6.1. Lead-free Process

# TEMPERATURE CONDITION GRAPH (TEMPERATURE ON BOARD PATTERN SIDE)



Pre-heat Hold time for  $150 \sim 180$  °C is  $60 \sim 120$  sec.



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## 7 PRODUCT QUALIFICATION AND TEST SEQUENCE

	Test Group									
Test or Examination	1	2	3	4	5	6	7	8	9	
		Test Sequence								
Examination of Product				1 . 7	1、6	1 \ 4			1	
Low Level Contact Resistance		1 \ 5	1 \ 4	2 \ 10	2、9	2 ` 5			3	
Insulation Resistance				3 . 9	3、8					
Dielectric Withstanding Voltage				4 \ 8	4 · 7					
Mating / Unmating Forces		2 \ 4								
Temperature rise	1									
Durability		3								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray						3				
Solder ability							1			
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Sample Size	2	4	4	4	4	4	2	4	4	